

## CM1211BIQ1 TYPE

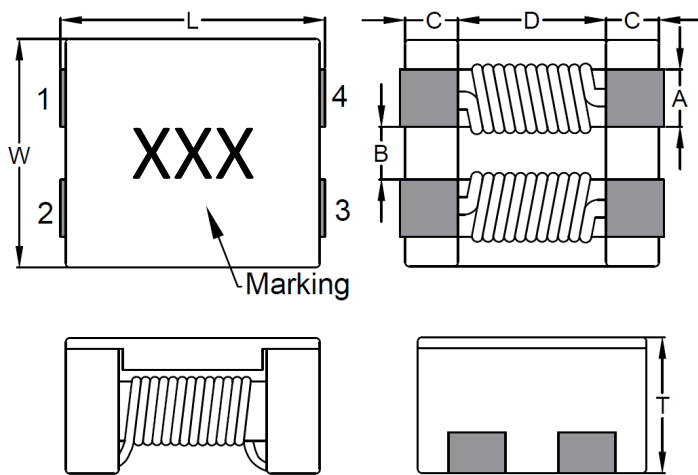
### ●FEATURE

1. Capable of handling the highest current of any chip-type common mode filter.
2. Noise is greatly suppressed.
3. AEC-Q200 Qualified

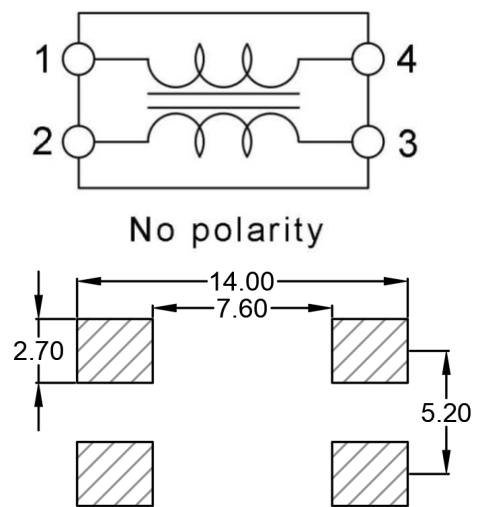
### ●Applications

1. Used for power line noise suppression for any electric devices. Used to counter adapter/battery line noise for relatively large electronic devices such as notebook , stand-alone word processor, etc.

### ●Shape and Dimension



### ●Schematics and Land Patterns(mm)



L=12.50±0.50mm ; W=10.80±0.50mm ; T=6.40mm Max. ;

A=2.70±0.50mm ; B=2.50±0.50mm ; C=2.50±0.50mm ; D=7.00mm Ref. ; Black cover ; Black marking

### ●Specification

Part number	Common mode Impedance (Ω)		DC Resistance (mΩ) Max.	Rated Current (A)	Rated Voltage (V)	Insulation Resistance (MΩ) Min.
	AT 100MHz					
CM1211BIQ1-800-1T	80 Min.	230 Typ.	2.0	10.0	125	10
CM1211BIQ1-501-3T	300 Min.	500 Typ.	5.5	8.0	125	10
CM1211BIQ1-701-4T	500 Min.	700 Typ.	6.0	8.0	125	10
CM1211BIQ1-801-4T	600 Min.	800 Typ.	8.0	8.0	125	10
CM1211BIQ1-102-5T	750 Min.	1000 Typ.	14.0	6.0	125	10

Note1. Measurement ambient temperature of Impedance, DCR and IDC : at 25°C

Note2. Test equipment: HP4294A

Note3. Packaging: Taping ; Quantity: 500 Pieces/Reel

## GENERAL CHARACTERISTICS

1. Operating temperature range: -55 TO + 125°C (Includes temperature when the coil is heated)
2. High temperature exposure(storage) refer MIL-STD-202 Method 108: 1000 hrs at rated operating temperature(e.g. 125°C). Part can be stored for 1000 hrs @125°C. Unpowered. Measurement at 24±4 hours after test conclusion.
3. Temperature cycling refer JESD22 Method JA-104: 1000 cycles(-55 TO + 125°C). Measurement at 24±4 hours after test conclusion. 30 min maximum dwell time at each temp. extreme. 1 min. maximum transition time.
4. Biased Humidity refer MIL-STD-202 Method 103: 1000 hours 85°C/85%RH. Unpowered. Measurement at 24±4 hours after test conclusion.
5. Operational Life refer MIL-PRF-27: 1000 hrs. at 125 °C tested. Measurement at 24±4 hours after test conclusion.
6. External Visual refer MIL-STD-883 Method 2009: Inspect device construction, marking and workmanship.
7. Physical Dimension refer JESD22 Method JB-100: Verify physical dimensions to the applicable device detail specification.
8. Resistance to Solvents refer MIL-STD-202 Method 215: Add aqueous wash chemical - OKEM clean or equivalent.
9. Mechanical Shock refer MIL-STD-202 Method 213: Figure 1 of Method 213. Condition C.
10. Vibration refer MIL-STD-202 Method 204: 5g;s for 20 minutes, 12 cycles each of 3 orientations. Test from 10-2000 Hz.
11. Resistance to soldering Heat refer MIL-STD-202 Method 210: Condition B No pre-heat of samples. Single wave solder-procedure 2 for SMD and procedure 1 for leaded with solder within 1.5mm of device body.
12. ESD refer AEC-Q200-002 or ISO/DIS 10605: Direct contact discharge 2kV.
13. Solderability refer J-STD-002: For both Leaded & SMD. Magnification 50X. Conditions: Leaded, Method A@235°C, category 3 ; SMD, a)Method B, 4hrs@125°C dry heat @235°C, b)Method B@215°C category 3., c)Method D category 3@260°C
14. Electrical Characterization refer spec: Show Min, Max Mean and Standard deviation at room from Min and Max temperature.
15. Flammability refer UL-94: V-0 or V-1 Acceptable.
16. Board Flex refer AEC-Q200-005: 60 sec minimum holding time.
17. Terminal Strength(SMD) refer AEC-Q200-006
18. Reflow profile recommend: J-STD-020-D Table 5-2